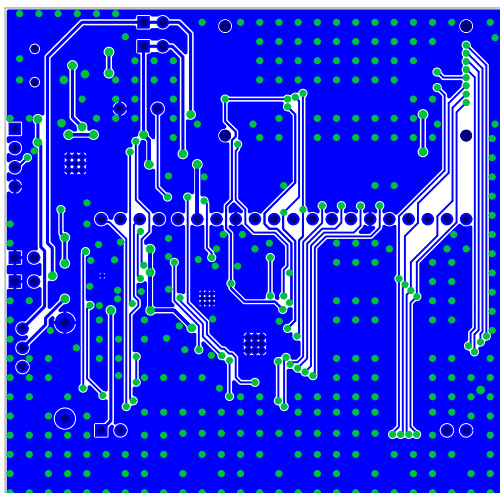
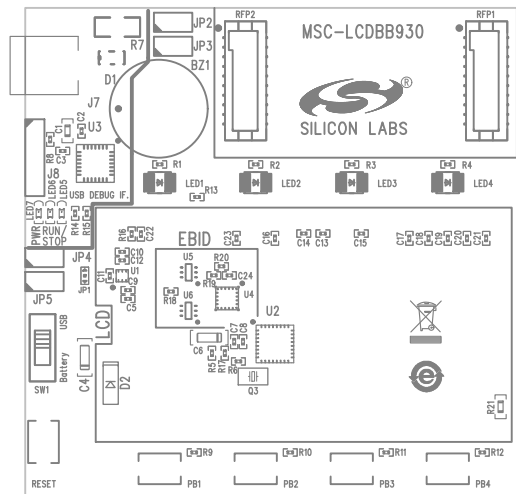


TOP WIRE

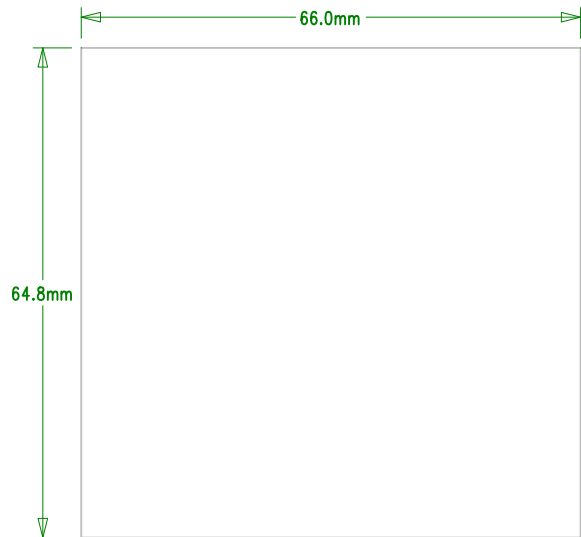


BOTTOM WIRE



TOP ASSEMBLY  
TOP SILKSCREEN





- MANUFACTURING NOTES: (UNLESS OTHERWISE SPECIFIED)
- 1. MATERIAL: COPPER CLAD EPOXY GLASS FR-4 BASE MATERIAL.  
COPPER CLADDING SHALL BE TYPE "HTE" WITH A WEIGHT OF 1/2 OZ/SQ FT. FOR EXTERNAL LAYERS AND 1/2 OZ/SQ FT. FOR INTERNAL LAYERS AND/OR PLANES.  
MINIMUM WEIGHT AFTER PLATING OF EXTERNAL LAYERS SHALL BE 1 OZ/SQ FT.
  - 2. TOTAL BOARD THICKNESS SHALL BE 1.63 +/-0.15 mm. LAYER SEQUENCING SHALL BE CONSECUTIVE AS ESTABLISHED BY THE MASTER PATTERN LAYER SCHEDULE SHOWN.
  - 3. LAYER TO LAYER REGISTRATION OF THE CONDUCTOR PATTERNS SHALL BE WITHIN 0.10 mm DIA. TRUE POSITION, WITH AN ABSOLUTE MINIMUM OF 0.05 mm BETWEEN PLATED-THRU HOLE WALLS AND ADJACENT CONDUCTIVE SURFACES. END PRODUCT LINE WIDTH AND TERMINAL AREAS SHALL NOT DEVIATE FROM THE 1:1 MASTER PATTERN IMAGE BY MORE THAN +0.025 mm, -0.075 mm FOR 1/2 OZ. COPPER.
  - 4. ALL PLATED-THROUGH HOLES TO HAVE A MINIMUM COPPER WALL THICKNESS OF 0.025 mm. PLATING SHALL BE CONTINUOUS. DO NOT FILL VIAS
  - 5. HOLE SIZE TOLERANCES SHALL BE:  
PLATED-THROUGH HOLES > 0.50 mm SHALL BE +/- 0.075 mm.  
UNPLATED THROUGH HOLES SHALL BE +/- 0.05 mm.  
TOLERANCES APPLY AFTER PLATING.
  - 6. FINISH: GOLDPLATED ON FOOTPRINTS AND PADS 0.0002 mm MAX.
  - 7. SOLDERMASK: SOLDERMASK OVER BARE COPPER - COLOR : BLUE
  - 8. SILKSCREEN: SILKSCREEN TOP SIDE ONLY USING NON-CONDUCTIVE WHITE EPOXY INK.
  - 9. THE PCB WARP AND TWIST SHALL NOT EXCEED 1 %
  - 10. HOLE TO EDGE TOLERANCE SHALL NOT VARY MORE THAN +/- 0.25 mm.
  - 11. ALL TOLERANCES ARE NON-ACCUMULATIVE.

